

REMARKS

Claims 1, 7, 13, and 14 have been amended, and new claims 15-17 have been added. Thus, claims 1-17 are pending in the present application. The claim amendments and new claims are supported by the specification and claims of the present application, with no new matter being added. Accordingly, favorable reconsideration of the pending claims is respectfully requested.

The specification has been amended to update the priority data to include the patent number of the issued parent application.

1. Rejections Under 35 U.S.C § 102

Claims 1-14 have been rejected under 35 U.S.C. § 102(e) as being anticipated by Publication No. US 2003/0062629 A1 to Moden (hereafter “*Moden*”) for the reasons set forth on pages 2-3 of the Office Action. Applicant respectfully traverses.

Claim 1 recites “providing a semiconductor die receiving member that is configured to receive a semiconductor die which can be mounted either through flip-chip mounting or wirebonding.” In addition, claim 1 has been amended to recite “a plurality of electrically conductive traces *routed through the die receiving member* to a plurality of terminal contact sites, each electrically conductive trace corresponding to one of said first contact sites and one of said second contact sites and providing electrical connection therebetween (emphasis added).” Support for this amendment can be found in the application as filed on page 9, lines 15-17. Independent claims 7, 13, and 14 recite similar limitations as discussed above for claim 1.

Only the embodiment of Figure 2 of *Moden* discloses a flip chip/wirebond configuration in which a semiconductor die can be mounted either through flip-chip mounting or wirebonding

on a board. Figure 2 of *Moden* particularly shows an attachment assembly 200 that includes a semiconductor die 12 having an active surface 14, with flip chip electric connections 16 extending from bond pads 15 of active surface 14. Electrical contact elements 21 on upper surface 20 of an adaptor board 18 communicate between each flip chip electric connection 16 to bond pads 28 through circuit traces 23 that are disposed on upper surface 20. A wire bond 34 extends from each bond pad 28 to a corresponding lead end 35 on a master board 30 (*see* p. 3, para. [0033]).

There is no teaching or suggestion in *Moden* for the embodiment of Figure 2 that the traces are “routed through the die receiving member” to a plurality of terminal contact sites as recited in claims 1, 7, 13, and 14. As discussed above, the embodiment of Figure 2 in *Moden* has traces 23 that are disposed on upper surface 20 of adaptor board 18, and thus are not “routed through” the board. While the embodiments of Figures 1, 3 and 4 in *Moden* do show traces 23 that are routed through adaptor board 18, none of these embodiments can receive a semiconductor die mounted either through “flip-chip mounting or wirebonding.” The embodiment of Figure 1 of *Moden* can only receive a semiconductor die mounted through flip-chip mounting, and the embodiments of Figures 3 and 4 of *Moden* can only receive a semiconductor die mounted through wirebonding.

Accordingly, claims 1-14 are not anticipated by *Moden*, and Applicant respectfully requests that the rejection of these claims under 35 U.S.C. § 102(e) be withdrawn.

2. New Claims

New independent claim 15 recites, *inter alia*, “providing a first semiconductor die and a second semiconductor die . . . for flip-chip mounting or wirebonding; mounting the first semiconductor die over the die receiving member in a flip chip configuration . . . and mounting the second semiconductor die over the die receiving member in a wirebonding configuration.” Support for these features of new claim 15 can be found in the application as filed on page 11, lines 5-20.

There is no teaching or suggestion in the cited reference of mounting first and second semiconductor dies in corresponding flip chip and wirebonding configurations over the same die receiving member as recited in claim 15.

New dependent claims 16 and 17 depend from claims 1 and 7, respectively, and relate to dual-purpose contact sites. Support for these claims can be found in the application as filed on page 12, lines 1-13. There is no teaching or suggestion in the cited reference of such dual-purpose contact sites.

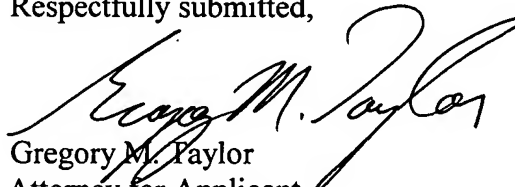
Accordingly, new claims 15-17 also present patentable subject matter.

CONCLUSION

In view of the foregoing, Applicant respectfully requests favorable reconsideration and allowance of the pending claims. In the event that the Examiner finds any remaining impediment to the prompt allowance of this application that may be clarified through a telephone interview, the Examiner is requested to contact the undersigned attorney.

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Respectfully submitted,



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